



## Materials Declaration Form

<b>IPC Form Type *</b>	<b>1752</b> Distribute	<b>Version</b>	<b>2</b>
<b>Sectionals *</b>	Material Info Manufacturing Info	<b>Subsectionals *</b>	A-D <i>* : Required Field</i>

Supplier Information			
<b>Company Name *</b>	<b>STMicroelectronics</b>	<b>Response Date *</b>	<b>2014-07-21</b>
<b>Contact Name *</b>	Refer to "Supplier Comment" section	<b>Contact Title</b>	Refer to "Supplier Comment" section
<b>Contact Phone *</b>	Refer to "Supplier Comment" section	<b>Contact Email *</b>	Refer to "Supplier Comment" section
<b>Authorized Representative *</b>	Antonella Lanzafame	<b>Representative Title</b>	AMS & IPD Materials Declaration Champion
<b>Representative Phone *</b>	Refer to "Supplier Comment" section	<b>Representative Email *</b>	Refer to "Supplier Comment" section
<b>Supplier Comment</b>	Online Technical Support - STMicroelectronics : <a href="http://www.st.com/internet/com/support/online_tech_support.jsp">http://www.st.com/internet/com/support/online_tech_support.jsp</a>		

**Uncertainty Statement**

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**Legal Statement**

<b>Supplier Acceptance *</b>	<b>true</b>	<b>Legal Declaration *</b>	<b>Standard</b>
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**Legal Statement**

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
	E1YM*UF46JC5	A	ZY1A	2014-07-21
Amount	UoM	Unit type	ST ECOPACK Grade	
109.00	mg	Each	ECOPACK® 2	

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		 life.augmented
3	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
Not Applicable ; if coating is used o	Tin (Sn), matte	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
DSO	9.7X4.4X0.9	28	gull wing	
Comment	TSSOP 28 BODY 4.4 PITCH 0.65; MD valid for CP:ST3243EBTR.			

QueryList : ROHS directive 2011/65/EU _ July 2011	
Query	Response
Product(s) meets EU RoHS requirement without any exemptions	true
Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	false
Product(s) meets EU RoHS requirements by application of the selected exemption(s)	false
Product(s) does not meet EU RoHS requirements and is not under exemptions	false
Product(s) is obsolete, no information is available	false
Product(s) is unknown, no information is available	false
Exemption Id.	Description

QueryList : REACH-16th December 2013				
Query				Response
The product does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration						Mfr Item Name	E1YM*UF46JC5					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Silicon die	Other inorganic materials	6.861	mg	supplier	Silicon die	Silicon (Si)	7440-21-3		6.691	mg	975222	61385
Silicon die			mg	supplier	Alloy	Aluminium (Al)	7429-90-5		0.055	mg	8016	505
Silicon die			mg	supplier	Alloy	Silicon Nitride (SiN)	68034-42-4		0.021	mg	3061	193
Silicon die			mg	supplier	Alloy	Silicon Oxide(SiO2)	7631-86-9		0.094	mg	13701	862
LEADFRAME	Copper and its alloy	51.532	mg	supplier	ALLOY	Copper (Cu)	7440-50-8		48.575	mg	942618	445642
LEADFRAME			mg	supplier	ALLOY	Nickel (Ni)	7440-02-0		1.515	mg	29399	13899
LEADFRAME			mg	supplier	ALLOY	Silicon (Si)	7440-21-3		0.328	mg	6365	3009
LEADFRAME			mg	supplier	ALLOY	Magnesium (Mg)	7439-95-4		0.076	mg	1475	697
LEADFRAME			mg	supplier	COATING	Silver(Ag)	7440-22-4		1.038	mg	20143	9523
DIE ATTACH	Other organic materials	1.474	mg	supplier	GLUE	Epoxy resin A	9003-36-5		0.103	mg	69878	945
DIE ATTACH			mg	supplier	GLUE	Epoxy resin B	68475-94-5		0.059	mg	40027	541
DIE ATTACH			mg	supplier	GLUE	Silver(Ag)	7440-22-4		1.135	mg	770014	10413
DIE ATTACH			mg	supplier	GLUE	Lactone	96-48-0		0.059	mg	40027	541
DIE ATTACH			mg	supplier	GLUE	Polyoxypropylenediamine	9046-10-0		0.059	mg	40027	541
DIE ATTACH			mg	supplier	GLUE	2,6-Diglycidyl phenyl allyl ether oligomer	proprietary		0.059	mg	40027	541
BONDING WIRE	Other inorganic materials	0.456	mg	supplier	BONDING WIRE	Gold (Au)	7440-57-5		0.456	mg	1000000	4183
ENCAPSULATION	Other inorganic materials	45.957	mg	supplier	MOLDING COMPOUND	Epoxy Resin	proprietary		4.136	mg	89997	37945
ENCAPSULATION			mg	supplier	MOLDING COMPOUND	Silica fused (SiO2)	60676-86-0		38.604	mg	840003	354165
ENCAPSULATION			mg	supplier	MOLDING COMPOUND	Phenol Resin	proprietary		2.987	mg	64996	27404
ENCAPSULATION			mg	supplier	MOLDING COMPOUND	Carbon Black	1333-86-4		0.23	mg	5005	2110
FINISHING	Other inorganic materials	2.72	mg	supplier	CONNECTION COATING	Tin (Sn)	7440-31-5		2.72	mg	1000000	24954